

## **IN THE CLAIMS**

1. (Currently amended) A clip containing ~~for holding~~ a stack of trays, ~~each tray containing pockets adapted to hold integrated circuits therein and~~ the stack having first and second opposing perimeter areas associated therewith, comprising:

a housing that defines a chamber containing ~~for holding~~ said stack therein, the chamber being accessible from an open front area and an open top area, without any support structure connecting between the open top area and open front area, said housing including:

a base adapted to support a bottom of the stack, said base having a front edge, first and second opposing edges, and a back edge;

a back wall that restrains the stack within said chamber; and

first and second side walls attached to said first and second opposing edges respectively adapted to restrain the stack laterally in said chamber; and

first and second resilient members attached at proximal ends to the respective first and second side wall and at distal ends to the back wall, wherein said first and second resilient members are adapted to resiliently move when the stack of trays is being inserted into said chamber in order to clamp the stack in the chamber once the stack is inserted into the chamber.

2. (Currently amended) The A clip of as-recited-in claim 1 wherein the back wall has a lower back surface and an upper back surface;

each of said first and second side walls have a front edge that defines a front height of the open front area, and a back edge of height less than said front height attached to a lower back surface of the back wall, and wherein said back wall has an upper back surface extending above said lower back surface; and

the first and second resilient members ~~and extension~~ have the proximal ends connected to a top portion of said first and second side walls, respectively, and the distal ends connected to an upper portion of said upper back surface of the back wall, wherein said members are adapted to resiliently move into a portion of an open sidewall area when clamping the stack in the chamber, and wherein said first and second resilient members extend inward into said chamber from said first and second side walls respectively.

3. (Currently amended) The A clip of as-recited-in claim 2, wherein the upper back surface of the back wall is resilient and is adapted to resiliently move in coordination with the first and second resilient members when the stack is being inserted into or removed from said chamber.

4. (Currently amended) The A clip of as-recited-in claim 3, wherein the top front edge of the first and second side walls are each resilient and adapted to move outwards to temporarily enlarge a width of the chamber when the stack is being inserted into or removed from said chamber.

5. (Currently Amended) The A clip of as-recited-in claim 4, further comprising ~~including~~ first and second tabs attached to a front portion of the first and second sidewalls, respectively, that each tab project into the chamber a predetermined distance and hold the stack in the chamber after the stack has been inserted into the chamber; and

wherein the top front edge of the first and second sidewalls are resilient so as to be movable outwards to temporarily enlarge the width of the chamber at a location of the first

and second tabs in an amount that corresponds to the predetermined distance until the stack has been inserted into or removed from the chamber.

6. (Currently amended) The A clip of as recited in claim 2, wherein the top front edge of the first and second side walls are each resilient and adapted to move outwards to temporarily enlarge a width of the chamber when the stack is being inserted into or removed from said chamber.

7. (Currently Amended) The A clip of as recited in claim 6, further comprising ~~including~~ first and second tabs attached to a front portion of the first and second sidewalls, respectively, that each tab project into the chamber a predetermined distance and hold the stack in the chamber after the stack has been inserted into the chamber; and

wherein the top front edge of the first and second sidewalls resilient so as to be movable outwards to temporarily enlarge the width of the chamber at a location of the first and second tabs in an amount that corresponds to the predetermined distance until the stack has been inserted into or removed from the chamber.

8. (Currently amended) The A clip of as recited in claim 1 wherein the back wall has a lower back surface and an upper back surface, and the upper back surface of the back wall is resilient and is adapted to resiliently move in coordination with the first and second resilient members when the stack is being inserted into said chamber.

9. (Currently amended) The A clip of as recited in claim 8 made by injection molding.

10. (Currently amended) The A clip of as recited in claim 8, wherein the top front edge of the first and second side walls are each resilient and adapted to move outwards to temporarily enlarge a width of the chamber when the stack is being inserted into or removed from said chamber.

11. (Currently amended) The A clip of as recited in claim 10 made by injection molding.

12. (Currently Amended) The A clip of as recited in claim 10, further comprising ~~including~~ first and second tabs attached to a front portion of the first and second sidewalls, respectively, that each tab project into the chamber a predetermined distance and hold the stack in the chamber after the stack has been inserted into the chamber; and

wherein the top front edge of the first and second sidewalls are resilient so as to be movable outwards to temporarily enlarge the width of the chamber at a location of the first and second tabs in an amount that corresponds to the predetermined distance until the stack has been inserted into or removed from the chamber.

13. (Currently amended) The A clip of as recited in claim 12 made by injection molding.

14. (Currently Amended) The A clip of as recited in claim 1, wherein a top front portion of the first and second side walls are each resilient and adapted to move outwards to temporarily enlarge a width of the chamber when the stack is being inserted into or removed from said chamber.

15. (Currently amended) The A clip of as recited in claim 14 made by injection molding.

16. (Currently Amended) The A clip of as recited in claim 14, further comprising ~~including~~ first and second tabs attached to a front portion of the first and second sidewalls, respectively, that each tab project into the chamber a predetermined distance and hold the stack in the chamber after the stack has been inserted into the chamber; and

wherein the top front edge of the first and second sidewalls are resilient so as to be movable outwards to temporarily enlarge the width of the chamber at a location of the first and second tabs in an amount that corresponds to the predetermined distance until the stack has been inserted into or removed from the chamber.

17. (Currently amended) The A clip of as recited in claim 16 made by injection molding.

18. (Currently amended) The A clip of as recited in claim 1 wherein said first and second resilient members are configured to limit application of pressure to a perimeter area of stack perimeter areas to clamp said stack.

19. (Currently amended) The A clip of as recited in claim 1 wherein said first and second resilient members are configured to apply pressure to both perimeter and non-perimeter areas of said stack..

20. (New) A clip containing a stack of trays for semiconductor components comprising:

a housing that defines a chamber containing the stack of semiconductor trays therein, the chamber being accessible from an open front area and an open top area;

a base adapted to support a bottom of the stack, said base having a front edge, and first and second opposing edges, wherein said base has a cut-out extending inwardly from the front edge;

a back wall that restrains the stack within said chamber; and

first and second side walls attached to said first and second opposing edges respectively adapted to restrain the stack laterally in said chamber.

21. (New) The clip of claim 20, wherein the cut out is located approximately in the center of the base.

22. (New) The clip of claim 20, wherein the first and second resilient members are attached at proximal ends to the respective first and second side wall and at distal ends to the back wall.

23. (New) The clip of claim 20, wherein a top front portion of the first and second side walls are each resilient and adapted to move outwards to temporarily enlarge a width of the chamber when the stack is being inserted into or removed from said chamber.

24. (New) The clip of claim 20, wherein said back wall extends orthogonally from the base and is substantially planar.

25. (New) The clip of claim 20, further comprising first and second tabs attached to a front portion of the first and second sidewalls, respectively, wherein each tab projects into the chamber a predetermined distance and secures the semiconductor stack in the chamber after the semiconductor stack has been inserted into the chamber.

26. (New) A clip containing a stack of trays for semiconductor components comprising:

a housing that defines a chamber containing the stack of semiconductor trays therein, the chamber being accessible from an open front area and an open top area;

a base adapted to support a bottom of the stack, said base having a front edge, and first and second opposing edges;

a back wall that restrains the stack within a back of said chamber; and

first and second side walls attached to said first and second opposing edges respectively adapted to restrain the stack laterally in said chamber;

first and second elongated members connected to a portion of said back wall; and

first and second open regions between said respective elongated members and said respective side walls.

27. (New) The clip of claim 26, wherein said first and second elongated members are attached at proximal ends to the respective first and second side wall and at distal ends to the back wall.

28. (New) The clip of claim 26, wherein a top front portion of the first and second side walls are each resilient and adapted to move outwards to temporarily enlarge a width of the chamber when the stack is being inserted into or removed from said chamber.

29. (New) The clip of claim 26, further comprising first and second tabs attached to a front portion of the first and second sidewalls, respectively, wherein each tab projects into the chamber a predetermined distance and confines the semiconductor stack in the chamber after the semiconductor stack has been inserted into the chamber.

30. (New) The clip of claim 26, further comprising a cut-out region that extends inwardly from the front edge of the base.

31. (New) A method for storing a stack of trays containing a plurality of semiconductor components in a clip comprising:

providing a clip having a back wall, a front opening, and opposing side walls;

pushing a stack of semiconductor trays into the front opening of the clip until the trays contact the back wall, and securing the semiconductor stack with resilient members integral with the clip, said resilient members contacting a perimeter area of the stack when a plurality of trays are inserted into the clip.

32. (New) The method of claim 31 wherein a cover is part of the semiconductor stack.

33. (New) The method of claim 31 wherein a portion of said side walls are resilient such that the sidewalls bend outwardly when the stack of trays is inserted into the front opening and collapse back when the stack is pushed against the back wall of the clip.

34. (New) The method of claim 31, wherein said back wall extends orthogonally from the base, and is substantially planar.

35. (New) The method of claim 31, further comprising removing the stack of trays by gripping a cut-out region extending inwardly from the base and pulling the trays out through the front opening.

36. (New) The clip of claim 31, further comprising first and second tabs attached to a front portion of the first and second sidewalls, respectively, wherein each tab projects into the chamber a predetermined distance and confines the semiconductor stack in the chamber after the semiconductor stack has been inserted into the chamber.